

08-22-2007



Docket No.: 075834-0056

To the Director of the U. S. Patent and

103438862

documents or the new address(es) below.

1. Name of Conveying Party(ies)

Sun Woon KIM, Seong Ju PARK, Ja Yeon KIM, Min Ki  
KWON, Dong Ju LEE, Jae Ho HAN

Additional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): July 18, 2007, July 16, 2007, July 16, 2007,  
July 16 2007, July 16, 2007, July 17, 2007  
(respectively)

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

2. Name and address of receiving party(ies)

Name: SAMSUNG ELECTRO-MECHANICS CO., LTD.

Internal Address:

Address: 314 Maetan 3-Dong, Yeongtong-Gu, Suwon,  
Gyeonggi-Do Republic of KOREA

Additional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application or patent number(s):

A. Patent Application No(s).

☐ This document is being filed together with a new application

B. Patent No(s).

11/889392

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

Phone Number: 202.756.8000

Fax Number: 202.756.8087

Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- ☐ Authorized to be charged by credit card  
☒ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

8. Payment Information:

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b. Deposit Account Number 500417  
Authorized User Name \_\_\_\_\_

9. Signature.

Stephen A. Becker, 26,527

Signature

August 13, 2007

Name and Registration No. of Person Signing

Date

Total number of pages including cover sheet, attachments and documents: 3

08/21/2007 DBYRNE 00000257 500417 11889392

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(SAB)

Docket No.: \_\_\_\_\_

### ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>KIM Sun Woon</u>	(4) <u>KWON Min Ki</u>
(2) <u>PARK Seong Ju</u>	(5) <u>LEE Dong Ju</u>
(3) <u>KIM Ja Yeon</u>	(6) <u>HAN Jao Ho</u>

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG Electro-Mechanics Co., Ltd.

314 Maetan 3-Dong, Yeongtong-Gu,

Suwon, Gyeonggi-Do

Republic of KOREA

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD OF MANUFACTURING NITRIDE-BASED SEMICONDUCTOR LIGHT EMITTING DIODE

(a) for which an application for United States Letters Patent was filed on \_\_\_\_\_, and identified by United States Serial No. \_\_\_\_\_; or

(b) for which an application for United States Letters Patent was executed on \_\_\_\_\_,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u>[Signature]</u> Name: KIM Sun Woon	<u>July 18, 2007</u>
2) <u>[Signature]</u> Name: PARK Seong Ju	<u>July 16, 2007</u>
3) <u>[Signature]</u> Name: KIM Ja Yeon	<u>July 16, 2007</u>
4) <u>[Signature]</u> Name: KWON Min Ki	<u>July 16, 2007</u>
5) <u>[Signature]</u> Name: LEE Dong Ju	<u>July 16, 2007</u>

INVENTORS

DATE SIGNED

6)

Han Jee Ho  
Name: HAN Jee Ho

July 17, 2007